EPOXIES
INNOVATIVE BONDING SOLUTIONS ETC.

TECHNICAL BULLETIN

20-3067
Epoxy Potting Compound

DESCRIPTION:

20-3067 is a high temperature epoxy potting and encapsulating system. This resin is designed for quick self leveling and outstanding electrical insulation properties. 20-3067B also provides excellent mechanical and chemical properties.

TYPICAL SPECIFICATIONS:

Color	Black	
Specific Gravity, 25ºC		
Resin	1.17	
Catalyst	1.22	
Viscosity, 25ºC, CPS		
Resin	15,000	
Catalyst	200	
Mix Ratio, by weight	100:85	
Mix Ratio, by volume	100:82	
Hardness, Shore D	87	
Tensile strength, Psi	11,300	
Elongation, %	3.0	
Flexural strength, Psi	17,500	
Compressive Strength, Psi	17,300	
Dielectric Constant, 60 Hz, 25ºC	3.26	
Dissipation factor, 60 Hz, 25ºC	.008	
Volume resistivity, 25ºC	> 2 X 10^{14}	
Tg, ºC	125	
Cure Schedule	90ºC	2 Hours
	125ºC	1 Hour

IMPORTANT:

The information in this brochure is based on data obtained by our own research and is considered accurate. However, no warranty is expressed or implied regarding the accuracy of this data, the results to be obtained from the use thereof or that any such use will not infringe any patent. This information is furnished upon the condition that the person receiving it shall make his own tests to determine the suitability thereof for his particular purpose.

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